MF430 ST



Ordering Information PART# RECEPTACLE MF430 ST ST -40°C to +85°C

BOTTOM VIEW

Applications

- Ethernet 10 or 100Mbps
- Token Ring
- Fibre Channel 266Mbps
- Short Wavelength FDDI
- Short Wavelength ATM-SDH/SONET 155Mbps
- Intra-Office Telecom
- General Purpose

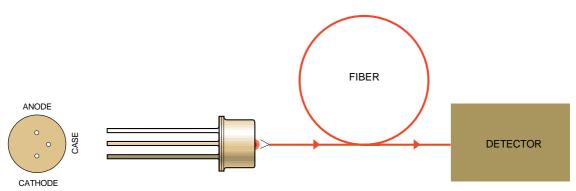
Features

- 865nm Surface-Emitting LED
- 250MHz Bandwidth
- Designed for 62.5/125µm Fiber
- Aligned in ST® Receptacle
- MTTF >1,000,000 hours

Description

This high performance LED has been designed for Datacom, Telecom or General Purpose Applications. The short wavelength LED allows cost-effective links over short distances. This very high speed device has an actively aligned receptacle for optimized coupling of power to 62.5/125µm fiber. A Silicon Photodiode is recommended as Receiver for this LED.

MF430 Functional Diagram



MF430 LED

Absolute Maximum Ratings*

Parameter	Symbol	Min.	Max.	Units
Storage Temperature	T _{stg}	-40	+85	°C
Operating Temperature (Fig 4)	T _{op}	-40	+85	°C
Electrical Power Dissipation (Fig 4)	P _{tot}		250	mW
Continuous Forward Current (f≤10kHz)	I _F		110	mA
Peak Forward Current (duty cycle ≤50%, f≥1MHz)	I _{FRM}		180	mA
Reverse Voltage	V_R		1.5	V
Soldering Temperature (Note 1)	T _{sld}		260	°C

^{*}Exceeding these values may cause permanent damage. Functional operation under these conditions is not implied. Note 1: 2mm from the case for 10s.

Optical & Electrical Characteristics (Case Temperature -25 to +70°C)

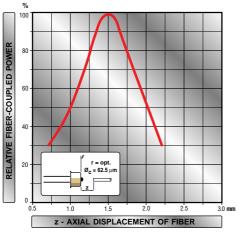
Parameter	Symbol	Min.	Тур.	Max.	Units	Test Conditions
Fiber-Coupled-Power (Fig 1, 2, 3)	P _{fiber}	-17.5			dBm	I _{Peak} =60mA (Note 1,2)
Rise & Fall Time (10-90%, no bias)	t _r t _f		1.5	2	ns	I _F =60mA (Note 2)
Bandwidth (3dB _{el})	f _c		250		MHz	I _F =60mA (Note 2)
Peak Wavelength	λρ	850	865	880	nm	I _F =60mA
Spectral Width (FWHM)	Δλ		50	60	nm	I _F =60mA
Forward Voltage (Fig 5)	V _F			2.1	V	I _F =60mA
Reverse Current	I _R			20	μA	V _R =1V
Capacitance	С		20		pF	V _R =0V, f=1MHz

Note 1: Average power at 10MHz/50% duty cycle. Measured at the exit of 100m of fiber.

Note 2: $62.5/125\mu m$ graded index fiber (NA = 0.275).

Thermal Characteristics

Parameter	Symbol	Min.	Тур.	Max.	Units
Thermal Resistance - Infinite Heat Sink	R _{thjc}			200	°C/W
Thermal Resistance - On PCB	R _{thjb}			300	°C/W
Temperature Coefficient - Optical Power	dP/dT _j		-0.6		%/°C
Temperature Coefficient - Wavelength	Δλ/dT _j		0.3		nm/°C



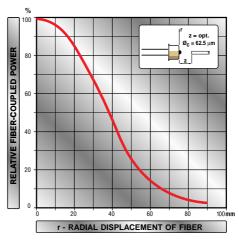
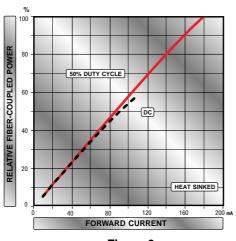


Figure 1





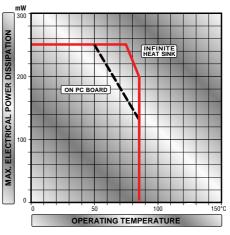


Figure 3

Figure 4

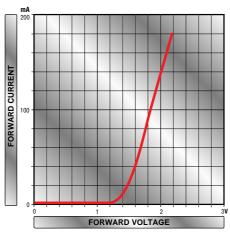
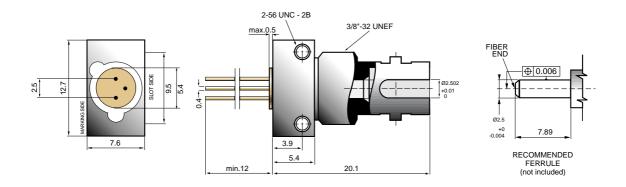


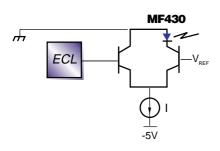
Figure 5

MF430 ST Mechanical Data

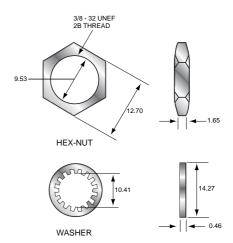


Note: The LED chip is isolated from the case. All dimensions in $\ensuremath{\mathsf{mm}}$.

Typical Drive Circuit



ST Packaging Hardware





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